**TI Designs: TIDA-01508**

**Sub 1-W, 16-Channel, Isolated Digital Input Module Reference Design**

**Description**
This reference design shows a compact implementation of 16 isolated digital input channels using TI’s ISO121x devices. The design works without an isolated supply and supports up to 100-kHz input signals (200-kbit) per channel. All 16 channels consume less than 1-W input power combined, which enables a compact layout and results in minimum heat dissipation. All input channels are designed to withstand ESD, EFT, and surge events according to IEC 61000-4-2. Furthermore, these channels can withstand input voltages of up to ±60 V.

**Features**
- 16 Digital Input Channels With up to ±60-V Input Voltage Tolerance
- Works With Primary Supply Only, No Isolated Power Supply Needed
- Parallel and Serial Output Option
- ±6-kV IEC 61000-4-2 ESD Performance
- Designed to Withstand ±2-kV Surge and EFT Burst Tolerant
- LaunchPad™ Header for Quick and Easy Evaluation

**Applications**
- Digital Input Modules
- Industrial Robot IO Modules

**Resources**
- TIDA-01508 Design Folder
- ISO1211 Product Folder
- ISO1212 Product Folder
- SN74LV165A Product Folder
- SN74LVC1GU04 Product Folder
- TVS3300 Product Folder

![TI E2E™ Community](image)

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1 System Description

This reference design shows a compact implementation of 16 isolated digital input channels using TI's new ISO121x devices, a single (ISO1211) and dual (ISO1212) channel, isolated, 24-V digital input receiver. The ISO121x device provides an accurate current limit for digital inputs, enabling a power dissipation of less than 1 W for 16 inputs channels. The 16 channels are divided into two groups of eight channels, each consisting out of three dual-channel ISO1212 and two single-channel ISO1211 devices.

ISO121x devices can be configured for IEC 61131-2 Type 1, 2, 3 compliant characteristics with only two external resistors, which are at the same time protecting the device itself against ESD, EFT, and surge events. In this design, all inputs are configured for Type 1.

Every channel is designed to withstand ESD, EFT, and surge events according to IEC 6100-4-2, IEC 6100-4-4, and IEC 6100-4-5, respectively. This protection is achieved by using pulse resistant resistors to configure ISO121x for Type 1. Furthermore, every input can withstand input voltages of up to ±60 V. For additional protection, every channel is either protected with a varistor or with two of TI's TVS3300 TVS diodes.

To read the output states of the 16 channels, each group of eight outputs is connected to a parallel-in serial-out register (SN74LV165A). The serial outputs of the two registers can be read out using the SPI of a microcontroller. Therefore, this reference design can be plugged onto the MSP430FR5969 LaunchPad or any other TI LaunchPad with the same SPI pinout. The LaunchPad also supplies power to the system.

For serial readout of the output states, the board is designed to support up to input signals of up to 100 kHz (200 kbit) per channel. However, ISO121x devices support data rates of up to 4 Mbps. For parallel readout, an additional 16-pin connector is mounted on the board.

1.1 Key System Specifications

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>SPECIFICATIONS</th>
<th>DETAILS</th>
</tr>
</thead>
<tbody>
<tr>
<td>Number of channels</td>
<td>16 (in groups of 8)</td>
<td>Section 2.3.1</td>
</tr>
<tr>
<td>Low level threshold = 0</td>
<td>12.5 V</td>
<td>Section 2.3.1</td>
</tr>
<tr>
<td>High level threshold = 1</td>
<td>13.65 V</td>
<td>Section 2.3.1</td>
</tr>
<tr>
<td>Typical threshold voltage hysteresis</td>
<td>1.2 V</td>
<td>Section 2.3.1</td>
</tr>
<tr>
<td>$I_{INX+SENSEX}$,typ</td>
<td>Typical sum of current drawn from IN and SENSE pins across temperature</td>
<td>2.2 mA per 2.47 mA per channel</td>
</tr>
<tr>
<td>$I_{INX+SENSEX}$,max</td>
<td>Maximum sum of current drawn from IN and SENSE pins across temperature</td>
<td>2.1 mA to 2.83 mA per channel; $30 \text{ V} &lt; V_{SENSE} &lt; 36 \text{ V}$</td>
</tr>
<tr>
<td>Power consumption</td>
<td>859 mW for 16 channels, 24 $V_{IN}$</td>
<td>Section 3.2.2.1</td>
</tr>
<tr>
<td>Maximum sampling speed, serial</td>
<td>100 kHz (200 kbps) per channel</td>
<td>Section 3.2.2.3</td>
</tr>
<tr>
<td>Maximum sampling speed, parallel</td>
<td>2 MHz (4 Mbps) per channel</td>
<td>Section 3.2.2.3</td>
</tr>
<tr>
<td>Thermal dissipation</td>
<td>43°C max after 1 hour of continuous operation, 24 $V_{IN}$, 25°C ambient temperature</td>
<td>Section 3.2.2.1</td>
</tr>
<tr>
<td>ISO121x CHARACTERISTICS</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Propagation delay</td>
<td>125 ns</td>
<td></td>
</tr>
<tr>
<td>Isolation rating</td>
<td>3 kV RMS</td>
<td></td>
</tr>
<tr>
<td>Working voltage</td>
<td>500 $V_{RMS}$ for 1 minute</td>
<td></td>
</tr>
<tr>
<td>Common-mode transient immunity</td>
<td>25 kV/µs</td>
<td></td>
</tr>
<tr>
<td>Maximum standoff voltage at input pins</td>
<td>±60 V</td>
<td></td>
</tr>
</tbody>
</table>
2 System Overview

2.1 Block Diagram

![Block Diagram of TIDA-01508](image)

Figure 1. Block Diagram of TIDA-01508

2.2 Highlighted Products

2.2.1 ISO121x

The ISO1211 and ISO1212 are isolated 24-V digital input receivers, compliant to IEC 61131-2 Type 1, 2, and 3 characteristics, and suitable for programmable logic controllers (PLCs) and motor-control digital input modules. Unlike traditional optocoupler solutions with discrete, imprecise current limiting circuitry, the ISO121x devices provide a simple, low-power solution with an accurate current limit to enable the design of compact and high-density I/O modules. These devices do not require field-side power supply and are compatible with high-side or low-side switches. The ISO121x devices operate over the supply range of 2.25 V to 5.5 V, supporting 2.5-V, 3.3-V, and 5-V controllers. A ±60-V input tolerance with reverse polarity protection helps ensure the input pins are protected in case of faults with negligible reverse current. These devices support up to 4-Mbps data rates passing a minimum pulse width of 150 ns for high-speed operation. The ISO1211 device is ideal for designs that require channel-to-channel isolation and the ISO1212 device is ideal for multichannel space-constrained designs.

Figure 2 shows the functional block diagram of one channel of the ISO121x family.

![Functional Block Diagram of ISO121x](image)

Figure 2. Functional Block Diagram of ISO121x
2.2.2 **SN74LV165A**

The SN74LV165A devices are parallel-load, 8-bit shift registers designed for 2-V to 5.5-V VCC operation. When the devices are clocked, data is shifted toward the serial output QH. Parallel-in access to each stage is provided by eight individual direct data inputs that are enabled by a low level at the shift/load (SH/LD) input. The SN74LV165A devices feature a clock-inhibit function and a complemented serial output, QH.

Figure 3 shows a functional block diagram of SN74LV165A.

![Figure 3. Functional Block Diagram of SN74LV165A](image)

2.2.3 **SN74LVC1GU04**

This single inverter gate is designed for 1.65-V to 5.5-V VCC operation. The SN74LVC1GU04 device contains one inverter with an unbuffered output and performs the boolean function \( Y = A \).

2.2.4 **TVS3300**

The TVS3300 is a transient voltage suppressor that provides robust protection for electronic circuits exposed to high transient voltage events. Unlike a traditional TVS diode, the TVS3300 precision clamp triggers at a lower breakdown voltage and regulates to maintain a flat clamping voltage throughout a transient overvoltage event. The lower clamping voltage combined with a low dynamic resistance enables a unique TVS protection solution that can lower the voltage a system is exposed during a surge event by up to 30% in unidirectional configuration and up to 20% in bidirectional configuration when compared to traditional TVS diodes.

2.3 **System Design Theory**

This section explains the digital input stage and readout functionality of the design.

2.3.1 **Digital Input Stage**

The 16 inputs of this reference design are built up in two groups of eight channels. Three dual-channel ISO1212 and two single-channel ISO1211 are used per group so that maximum flexibility is provided to the user. Figure 4 and Figure 5 show the input stages of one ISO1212 and one ISO1211, respectively. Although not visible in these figures, pin FGND of the ISO1211 as well as pins FGND1 and FGND2 of the ISO1212 are all connected to input port FGND, which is the common field ground of all digital inputs.
Every input of the ISO1211 can be configured for Type 1, 2, 3 characteristics according to IEC 61131-2 with resistors $R_{THR}$ and $R_{SENSE}$. In addition, an input capacitor $C_{IN}$ is connected after $R_{THR}$ to GND creating an RC filter with $R_{THR}$ for further protection against ESD, EFT, and surge events. To withstand high pulse voltages, $R_{THR}$ is selected as a pulse proof resistor. Table 2 shows the configuration for Type 1 and 3 digital inputs as well as the resulting voltage ratings according to IEC 61002-4-2, IEC 61002-4-4, and IEC 61002-4-5 for specific values of $R_{THR}$, $R_{SENSE}$, and $C_{IN}$, respectively.

<table>
<thead>
<tr>
<th>IEC 61131-2 TYPE</th>
<th>$R_{SENSE}$</th>
<th>$R_{THR}$</th>
<th>$C_{IN}$</th>
<th>SURGE</th>
<th>ESD</th>
<th>IEC EFT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Type 1</td>
<td>562</td>
<td>3 kΩ</td>
<td>10 nF</td>
<td>±1 kV</td>
<td>±6 kV</td>
<td>±4 kV</td>
</tr>
<tr>
<td>Type 3</td>
<td>562</td>
<td>1 kΩ</td>
<td>330 nF</td>
<td>±1 kV</td>
<td>±6 kV</td>
<td>±4 kV</td>
</tr>
</tbody>
</table>

To protect the inputs against surge events with even higher ratings, all inputs are as well protected with either a varistor or two TVS3300 TVS diodes. Those devices are placed in parallel to $C_{IN}$.

In this design, all channels as configured for Type 1 inputs with $R_{THR}$ = 2.4 kΩ and $R_{SENSE}$ = 562 Ω. The typical high-level threshold $V_{IH}$ and minimum low-level threshold $V_{IL}$ at the ISO121x input (include $R_{THR}$) for output high and low are given by Equation 1 and Equation 2.

$$V_{IH} \ (\text{typ}) = 8.25 \ V + R_{THR} \times \frac{2.25 \ mA \times 562 \ \Omega}{R_{SENSE}} = 13.65 \ V$$  \hspace{1cm} (1)

$$V_{IL} \ (\text{min}) = 7.1 \ V + R_{THR} \times \frac{2.25 \ mA \times 562 \ \Omega}{R_{SENSE}} = 12.5 \ V$$  \hspace{1cm} (2)
### 2.3.2 Readout of Digital Outputs

To readout the 16 digital output signals, there exist two options:

1. Parallel readout of output signals at connectors J5 (channels 1–8) and J8 (channels 9–16)
2. Serial readout of output signals from parallel-in serial-out registers U1 and U2

![Schematic of Parallel and Serial Readout Options for Output Signals](image)

**Figure 6. Schematic of Parallel and Serial Readout Options for Output Signals**

For serial readout, all eight output signals per group are connected to the parallel-in serial-out register SN74LV165A. The output QH of register U1 is connected to input pin SER of register U2. To readout the register, the SPI of the LaunchPad is used. For this, the LaunchPad SPI is connected to the SN74LV165A registers as shown in Table 3:

<table>
<thead>
<tr>
<th>LAUNCHPAD</th>
<th>U1 (CHANNELS 1–8)</th>
<th>U2 (CHANNELS 9–16)</th>
</tr>
</thead>
<tbody>
<tr>
<td>SPI_MOSI</td>
<td>Not used</td>
<td>Not used</td>
</tr>
<tr>
<td>SPI_MISO</td>
<td>Not connected</td>
<td>QH</td>
</tr>
<tr>
<td>SPI_nCS</td>
<td>SH/LD</td>
<td>SH/LD</td>
</tr>
<tr>
<td>SPI_CLK</td>
<td>CLK</td>
<td>CLK</td>
</tr>
<tr>
<td></td>
<td>QH</td>
<td>SER</td>
</tr>
</tbody>
</table>

**NOTE:** The SPI_nCS signal of the LaunchPad is inverted using a logic gate SN74LVC1GU04 with function \( Y = \bar{A} \).

\[ \rightarrow \text{SPI_nCS logic '0' / low = logic '1' / high at SH/LD pin of SN74LV165A} \]

The readout of the 16 output states works as follows:

1. SPI_nCS is high \( \rightarrow \) both SN74LV165A continuously load input states
2. SPI_nCS pulled low \( \rightarrow \) both SN74LV165A store current status of their respective eight inputs
3. SPI_CLK is clocked 16 times \( \rightarrow \) output QH of register U2 first gives out outputs states of inputs H–A (channel 9–16) of U2, second gives out output states H–A (channel 1–8) of U1.
3 Hardware, Software, Testing Requirements, and Test Results

3.1 Required Hardware and Software

The board can be powered and interfaced over connectors J1–J4. Figure 7 shows a snapshot of the interface. To simplify the evaluation, it is recommended to use a LaunchPad like the MSP430FR5969 or the CC3220 to power and interface the board.

Figure 7. BoosterPack Interface of TIDA-01508

3.1.1 Hardware

- Laptop
- MSP430FR5969 LaunchPad
- Signal generator and scope: National Instruments Virtual Bench
- Precision source measure unit (SMU): Keysight B2912A

3.1.2 Software

For parallel readout of the output signals of the ISO121x devices, no special hardware is required. For serial readout using registers U1 and U2, program an SPI routine as described in Section 2.3.2.
3.2 Testing and Results

3.2.1 Test Setup

This reference design is plugged onto an MSP430™ LaunchPad, which is connected over USB to a laptop. The laptop is used to readout these stored values. Registers U1 and U2 are read out using the SPI of the LaunchPad. The LaunchPad performs multiple readout and stores the data in its memory. Afterwards, the information is sent to the laptop using the USB interface of the LaunchPad. To generate the digital input signals, test the voltage thresholds, and to measure the power consumption, the SMU is used.

Figure 8 shows a simple picture of the test setup.

Figure 8. Test Setup of TIDA-01508

3.2.2 Test Results

3.2.2.1 Power Dissipation and Thermal Images

To test the power dissipation of the 16 inputs, a 24-V signal is connected from the SMU to each input. The current that is drawn from the inputs is measured by the same SMU. The setup is left running for one hour, then the current measured and a thermal image is taken.

All 16 inputs together draw a current of 35.8 mA. Therefore, the power dissipation of all 16 channels together is 24 V × 35.8 mA = 859.2 mW. This means that every channel is only drawing 2.2375 mA in average.

The thermal images show that the two channel devices (ISO1212) heat up to 43°C (see Figure 9). The ambient temperature is around 25.8°C, which is a difference of 17.2°C. Furthermore, this difference shows that the devices only dissipate a small amount of energy, which enables to use them also in applications with high ambient temperatures.
Next, the input signals are changed to 30 V and the test is repeated. The resulting input current is now 36.3 mA, which results in a power dissipation of 1089 mW. Hence, every channel is only drawing 2.26875 mA in average. Furthermore, this value shows that even for input voltages, the input current stays low.

The power dissipation of the rest of the board is also measured. For an input voltage of 3.3 V, the board consumes 41 mA, which results in an additional 135-mW power dissipation, dominated by the LED power dissipation. This value is the same for 24-V inputs and 30-V inputs.

### 3.2.2.2 Serial Readout of Output States

Figure 10 shows the CLK and MISO signal lines of the SPI for the readout of 16 channels. The output states of the channels are 0-0-1-1-1-0-1 and 1-1-0-1-1-0-1-0 (channels 9–16 and channels 1–8, respectively). The SPI is running at a frequency of 8 MHz. The overall readout procedure takes around 6 µs. This results in a readout frequency of around 167 kHz.

There is a delay between the readout of the first eight channels and the second eight channels. In a final application, this delay can be optimized to achieve higher readout frequencies.
Figure 10. Readout Procedure With SPI Running at 8 MHz

Figure 11 shows the readout procedure for the first eight channels when the SPI is running at 16 MHz. This results in a readout time for eight output states of only 600 ns. Also for this higher speed, the readout works fine.

Figure 11. Readout Procedure With SPI Running at 16 MHz
3.2.2.3 Input Switching Frequency

Both TVS3300 and varistor inputs are tested up to 100 kHz by using the signal generator of the SMU. Because the signal generator only supports signals up to 12 V peak to peak, the voltage threshold resistor $R_{\text{THR}}$ has been removed for this test so that the voltage thresholds of the ISO121x are low enough. The signal is set to 12 V peak to peak, rectangular waveform, 100 kHz.

The outputs of the ISO121x are measured with a scope. Furthermore, a 150-mΩ resistor is placed between the GND of this reference design and the actual GND of the power supply to observe peak currents with a scope. Figure 12 shows an input protected with the TVS3300, and Figure 13 shows an input protected with the varistor.

![Figure 12. Switching of Outputs and Peak Currents With TVS Protection](image-url)
For both protection schemes, the switching can go up to 100 kHz without any problem. Furthermore, when the 12-V signal is switching, a peak current of $200 \text{ mV}/150 \text{ m} \Omega = 1.3 \text{ A}$ is flowing for a very short time. This is due to the input capacitor in front of the ISO121x.
4 Design Files

4.1 Schematics
To download the schematics, see the design files at TIDA-01508.

4.2 Bill of Materials
To download the bill of materials (BOM), see the design files at TIDA-01508.

4.3 PCB Layout Recommendations
For layout guidelines regarding the digital input stage, refer to the Layout section of *ISO121x Isolated 24-V to 60-V Digital Input Receivers for Digital Input Modules*.

4.3.1 Protection Circuit Input Stage
Figure 14 shows the two input stages of one ISO1212 from left to right. In this case, the protection circuit consists of the resistor \( R_{\text{THR}} \) and a varistor. Depending on the channel, the varistor can also be replaced by two TVS3300 devices. The two smaller components next to the ISO1211 input pins are the input capacitor \( C_{\text{IN}} \) and the sense resistor \( R_{\text{SENSE}} \).

![Figure 14. Input Protection Stage of ISO1212](image)

As described in Section 2.3.1, \( R_{\text{THR}} \) is a pulse proof resistor in a 0207 footprint. After \( R_{\text{THR}} \) is passed, the signal line is first routed through the pads of the TVS3300, and varistors before it are connected to the pads of \( C_{\text{IN}} \) and \( R_{\text{SENSE}} \). This connection ensures that in case of ESD, EFT, or surge events, the protection stage is always passed first before any possibly damaging voltage or current strikes reach the ISO121x. Furthermore, this results in a distance around 8 mm between the high-voltage side or left pad of \( R_{\text{THR}} \), where the ESD, EFT, or surge event hits first, and the pad of \( C_{\text{IN}} \). This distance results in additional protection against voltage spikes.

In general, do not place the resistor pad connected to external high voltage within 4 mm of the ISO121x device pins or the \( C_{\text{IN}} \) and \( R_{\text{SENSE}} \) pins to avoid flashovers during EMC tests (refer to the Layout section of *ISO121x Isolated 24-V to 60-V Digital Input Receivers for Digital Input Modules*).

4.3.2 Layout Prints
To download the layer plots, see the design files at TIDA-01508.

4.4 Altium Project
To download the Altium project files, see the design files at TIDA-01508.
4.5 Gerber Files
To download the Gerber files, see the design files at TIDA-01508.

4.6 Assembly Drawings
To download the assembly drawings, see the design files at TIDA-01508.

5 Software Files
To download the software files, see the design files at TIDA-01508.

6 Related Documentation
1. Texas Instruments, *ISO121x Isolated 24-V to 60-V Digital Input Receivers for Digital Input Modules Data Sheet*
2. Texas Instruments, *SNx4LV165A Parallel-Load 8-Bit Shift Registers Data Sheet*
3. Texas Instruments, *SN74LVC1GU04 Single Inverter Gate Data Sheet*
4. Texas Instruments, *TVS3300 33-V Precision Surge Protection Clamp Data Sheet*

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7 About the Author
TOBIAS PUETZ is a systems engineer in the Texas Instruments Factory Automation and Control team, where he is focusing on PLC and robotics. Tobias brings to this role his expertise in various sensing technologies as well as power design. Tobias earned his master's degree in electrical engineering and information technology at the Karlsruhe Institute of Technology (KIT), Germany in 2014.

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